Title (en)

PROCESS FOR FABRICATING A MASK WITH SUBMILLIMETRE APERTURES FOR THE PRODUCTION OF A SUBMILLIMETRE GRID, AND SUBMILLIMETRE GRID

Title (de)

VERFAHREN ZUR FABRIKATION EINER MASKE MIT ÖFFNUNGEN IM SUBMILLIMETERBEREICH ZUR HERSTELLUNG EINES GITTERS IM SUBMILLIMETERBEREICH SOWIE GITTER IM SUBMILLIMETERBEREICH

Title (fr)

PROCEDE DE FABRICATION D'UN MASQUE A OUVERTURES SUBMILLIMETRIQUES POUR LA REALISATION D'UNE GRILLE SUBMILLIMETRIQUE, GRILLE SUBMILLIMETRIQUE

Publication

EP 2129632 A2 20091209 (FR)

Application

EP 08775743 A 20080321

Priority

• FR 2008050505 W 20080321
• FR 0753972 A 20070321

Abstract (en)

[origin: FR2913972A1] Production of a mask on part of a functional glass substrate involves (a) applying a first layer using a solution of stabilized, dispersed colloidal particles in a solvent and (b) drying the first layer until a mask-forming network of straight-sided interstices is formed. An independent claim is included for a grid produced by the process, having a ratio of spacing between the strands to width of the strands of 7-20.

IPC 8 full level

C03C 17/00 (2006.01); **C03C 17/06** (2006.01); **C03C 17/22** (2006.01); **H01L 51/52** (2006.01); **H01L 51/56** (2006.01)

CPC (source: EP KR US)

B82Y 20/00 (2013.01 - EP US); **B82Y 30/00** (2013.01 - EP US); **C03C 4/00** (2013.01 - KR); **C03C 17/00** (2013.01 - KR); **C03C 17/002** (2013.01 - EP US); **C03C 17/06** (2013.01 - EP US); **C03C 17/22** (2013.01 - EP KR US); **H10K 10/82** (2023.02 - US); **H10K 50/805** (2023.02 - US); **H10K 71/00** (2023.02 - US); C03C 2217/252 (2013.01 - EP US); C03C 2218/116 (2013.01 - EP US); C03C 2218/34 (2013.01 - EP US); G02F 1/155 (2013.01 - EP US); G02F 2001/1555 (2013.01 - EP US); H10K 2102/331 (2023.02 - EP US); Y10T 428/24802 (2015.01 - EP US); Y10T 428/24926 (2015.01 - EP US)

Designated contracting state (EPC)

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